Technical Specification

[GENERATOR]

Ultrasonic-frequency	Auto control 60KHz± 5
Ultrasonic-power	Rating $15W(max)$
	Effective I 0W (max)
Temperature range	200℃~500℃
Power setting	Variable(multi-choice)
Power Requirements	AC100V/240V、50/60Hz、
Dimension	W210 x H90 x D235
Weight	app. 5kg

KHz 150W [IRON] Transducer

Tip material Tip diameter Heater Dimension Weight

Langevin type (P.Z.T.) 60 kHz Stainless steel @4.0mm (Std.)* High performance sheathed heater 65W @36mm (max) x 250mm app. 210 g (with cord) *The tip shape is supported nonstandard type.

SUNBONDER[®] ULTRASONIC SOLDERING SYSTEM USM-5

Accessories

Soldering iron stand	1
Power source cord	1
Spanner for changing tip	1
Fuse	2





For operating the device, refer to the instruction manuals. Don't use near water, under conditions of high humidity, dust and soot filled places, to avoid electric shock, fire or breakdown.

Soul in Technology **KURODA-TECHNO Co., Ltd.**

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ULTRASONIC SOLDERING **SYSTEM SUNBONDER® USM-5**

SUNBONDER is an ultrasonic soldering device that produces high quality soldered joints. The soldering iron consists of a high performance sheath heater and transducer, supplying heat and ultrasonic oscillations to the tip. Using CERASOLZER, a solder alloy especially formulated for use with the SUNBONDER, you can easily solder directly to glass, ceramics and other low solderability materials, such as Al, Mo, or stainless steel. The application field of ultrasonic soldering technology is large due to the fact that SUNBONDER and CERA-SOLŽER can be used with a wide range of different materials, such as metals, semiconductors, glass and ceramic substrates.

Soldering to glass, ceramics and low solderability metals

CERASOLZER is used for soldering to glass, ceramic and low solderability metals. CERASOLZER is a special solder alloy with addition of Zn, Sb, Al, Ti, Si, In, and Cu.A strong chemical bond of Zinc and Oxygen is achieved between the substrate and CERASOLZER by applying ultrasonic oscillation with SUNBONDER device to the melting CERASOLZER solder alloy. This superior bonding technique provides an excellent airtight, weatherproof, humidity resistant seal as well as joints with good electroconductivity between interconnected layers.



Ultrasonic soldering makes it possible to solder glass, ceramics and low-solderability metals, such as Al, Mo, stainless steel etc.

BACK VIEW POWER SW AC100/240V Change SW FUSE 250V 3 A*2pc AC inlet LAN MONITORING FOOT SW CONNECTOR (Same as front) **XOPTION** (%Ext. control is option)



SUNBONDER features

(1) Direct soldering to glass, ceramics, low solderability metals

(2) Stable ultrasonic frequency with constant amplitude control and new feedback system for

automatic-adjustment of resonance frequency.

(3) Adjustable ultrasonic-power output.

(4) Heater temperature is possible to adjust between 200-500°C at intervals of 10° C.

(5) Soldering condition is possible to reproduce by display ultrasonic-frequency, ultrasonic-power and heater temperature.

(6) Compact handy type, portable hand and spacesaving.

- (7) Easy to operate.
- (8) Variable power supply with AC100V/240V switch.

Applications

Soldering to glass or ceramics

- Soldering to low solderability metals
- Lead bonding for superconductive materials
- Lead bonding for solar cells or modules
- Lead bonding on the surface of display